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Mechanisms of material removal and subsurface damage in fixed-abrasive diamond wire slicing of single-crystalline silicon

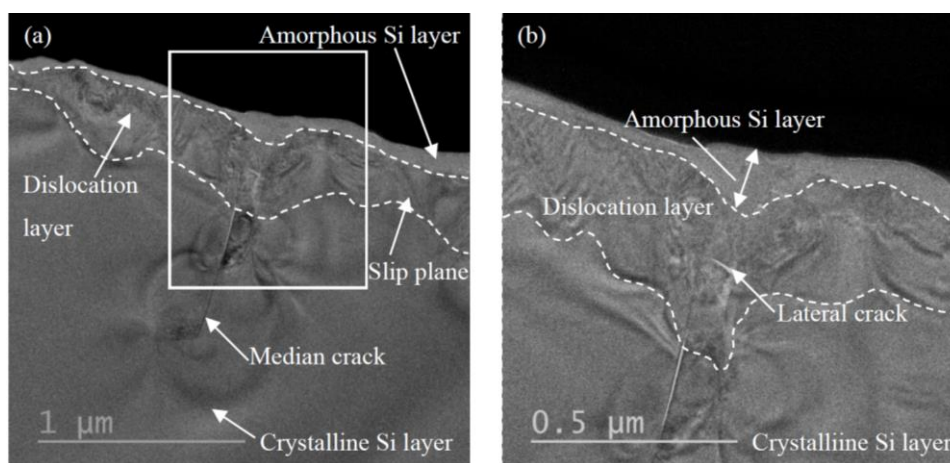
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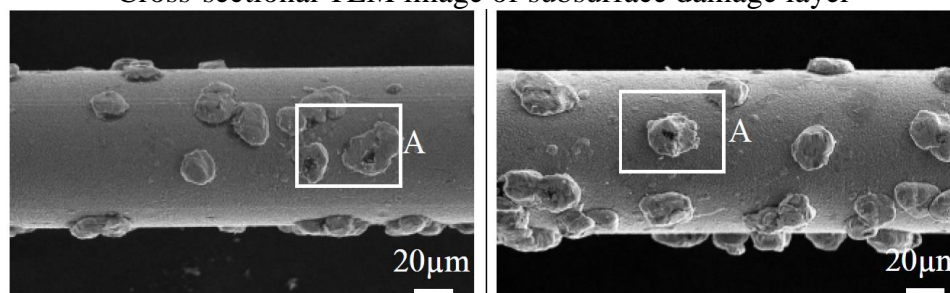
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Graphical abstract



Cross-sectional TEM image of subsurface damage layer



SEM image of diamond wire after slicing

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